

ABSTRACT

Disclosed is a die-bonding film for bonding a semiconductor chip to a support member on which the semiconductor chip is mounted. An elongation at break at -15°C of this die-bonding film is 5% or less.

5 Furthermore, this die-bonding film contains an epoxy resin, an epoxy resin curing agent, and an epoxy group-containing (meth)acrylic copolymer, and a total content of the epoxy resin and the epoxy resin curing agent is 10% by mass or more and less than 30% by mass on the basis of a total amount of the epoxy resin, the epoxy resin curing agent,
10 and the epoxy group-containing (meth)acrylic copolymer. An elongation at break at -15°C of the die-bonding film is 5% or less.

No Suitable Figure